Abstract of the Disclosure

A method of dividing a semiconductor wafer of which the surface has a plurality of chips sectioned by streets, into individual chips, characterized in that it comprises a scribing step in which division guide lines are formed by drawing scribed lines along the streets on the surface of the semiconductor wafer, a tape sticking step in which a tape is stuck onto the surface having the division guide lines formed thereon, of the semiconductor wafer, and a back surface cutting step in which cutting grooves are formed in the back surface, to which the tape is stuck, of the semiconductor wafer such that a bit of uncut portions are left along the division guide lines.

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